

## REMARKS

Claims 3-12, 14, and 15 remain in the application for consideration of the Examiner.

Reconsideration and withdrawal of the outstanding rejections are respectfully requested in light of the above amendments and following remarks.

Claims 3, 5-10, 12, 14, and 15 were rejected under 35 U.S.C. § 103 as being unpatentable over Nichols '575 and Nichols '662; and Claims 4 and 11 were rejected under 35 U.S.C. § 103 as being unpatentable over Nichols '575 and Nichols '662 in view of De Luna.

These rejections are respectfully traversed.

It is respectfully submitted that Nichols '575 does not disclose or suggest the presently claimed invention including wherein the first registration feature is incompatible with the second registration feature in independent Claims 3 and 14.

The Examiner alleges that Nichols '575 discloses a first registration feature 20 and a second registration feature 22.

Notwithstanding the allegations of the Examiner, there is nothing to indicate in Nichols '575 that indicates that these two features are incompatible.

The Examiner's attention is directed to page 2, line 7 of the instant application. Here, Applicants found that there is a known anodized aluminum wafer cassette for high-temperature wafer processing manufactured by Advanced Semiconductor Manufacturing referred to as ASM high-temperature cassette specifically designed for high-temperature wafer processing in certain reactors manufactured by the same company. In some instances, it is desirable to use these high-temperature anodized

aluminum wafer cassette for carrying semiconductor wafers during high-temperature processing operations and to use "semi-standard" PFA Teflon cassettes "Teflon cassettes" for carrying the same wafers during other low temperature operations. However, these PFA Teflon cassettes and the ASM high-temperature cassettes have different registration features. As a consequence, the ASM high-temperature cassettes cannot be used in any single available wafer transfer machine to transfer semiconductor wafers from either the "semi-standard" PFA Teflon cassettes into the ASM high-temperature cassettes or vice versa. Instead, two separate wafer transfer machines are required.

The reference to Nichols could not achieve this advantage.

Nichols '662 does not cure these defects. In particular, Nichols '662 does not disclose or suggest the presently claimed invention including the first registration feature being incompatible with the second registration feature as defined in independent Claims 3 and 14.

Nichols '662 discloses a larger wafer carrier and a smaller wafer carrier.

Similar to Nichols '575, nothing discloses the presently claimed invention.

Whether or not De Luna discloses a handle for moving a pushing member and whether it would have been obvious to one of ordinary skill in the art is of no moment since the resulting construction would no way disclose or suggest the presently claimed invention.

In light of the above, it is respectfully submitted that the present application is in condition for allowance, and notice to that effect is respectfully requested.

While it is believed that the instant response places the application in condition for allowance, should the Examiner have any further comments or suggestions, it is

respectfully requested that the Examiner contact the undersigned in order to expeditiously resolve any outstanding issues.

To the extent necessary, Applicant petitions for an Extension of Time under 37 CFR 1.136. Please charge any fees in connection with the filing of this paper, including extension of time fees, to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,



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